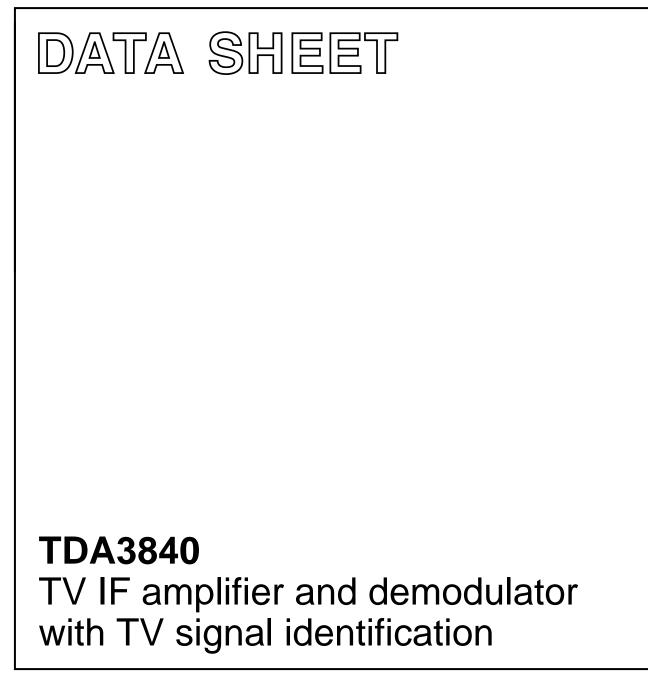
INTEGRATED CIRCUITS



Preliminary specification File under Integrated Circuits, IC02 April 1991



TDA3840

FEATURES

- Low supply voltage range, from 5.0 V to 8.0 V
- Low power dissipation, 200 mW at 5 V $\,$
- High supply ripple rejection
- Wide IF bandwidth of 80 MHz
- Synchronous demodulator with low differential phase and gain
- Additional video buffer with a wide bandwidth of 10 MHz
- Video off switch
- Peak sync AGC
- Adjustable take-over point (TOP); positive AGC slope
- Switching to fast AGC dependent on TV identification
- Alignment free AFC detector with integrated phase shift
- ESD protection
- TV signal identification
- · Options: tracking of reference circuit

QUICK REFERENCE DATA

GENERAL DESCRIPTION

The TDA3840 is a bipolar integrated circuit for vision IF-signal processing in TV and VTRs, designed for a supply voltage range from 5.0 V to 8.0 V.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _P	supply voltage range (pin 15)		4.75	5.0	8.8	V
IP	supply current (pin 15)	V _P = 5.0 V	_	42	-	mA
V _{1-20(rms)}	IF input signal for nominal video output f = 38.9 MHz voltage at pin 14 (RMS value)		-	70	-	μV
	minimum IF input signal for TV signal identification at pin 6 (RMS value)	maximum G _v	-	20	40	μV
Vo	video output signal (pin 12)	buffered	_	2.0	-	V
G _v	IF voltage gain control range		_	66	-	dB
S/N	signal-to-noise ratio	V ₁₋₂₀ = 10 mV	55	60	_	dB
V ₈	AFC output voltage swing		_	4.0	_	V
S _{AFC}	AFC steepness (pin 8)		_	2	-	μA/kHz
RR	supply voltage ripple rejection (pin 12)		30	35	_	dB

ORDERING INFORMATION

EXTENDED	PACKAGE					
TYPE NUMBER	PINS	PIN POSITION	MATERIAL	CODE		
TDA3840	20	DIL	plastic	SOT146 ⁽¹⁾		
TDA3840T	20	mini-pack	plastic	SO20L; SOT163A ⁽²⁾		

Note

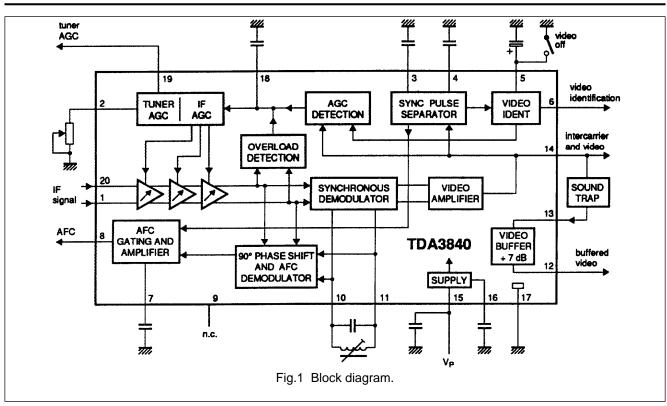
1. SOT146-1; 1996 December 13.

2. SOT163-1; 1996 December 13.

DESCRIPTION

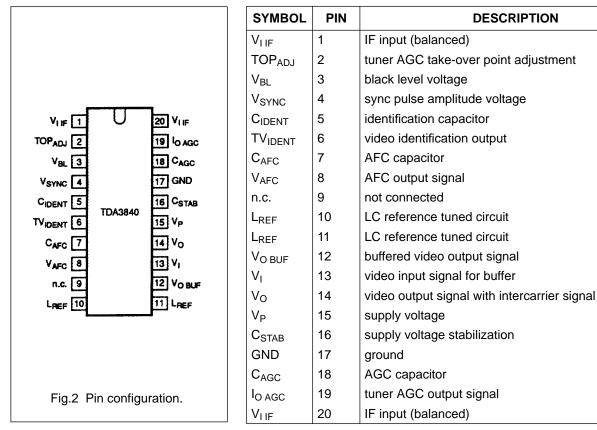
TV IF amplifier and demodulator with TV signal identification

TDA3840



PIN CONFIGURATION

PINNING



TDA3840

TV IF amplifier and demodulator with TV signal identification

FUNCTIONAL DESCRIPTION

The complete circuit consists of the following functional blocks as shown in Fig.1:

- 1. 3-stage gain controlled IF amplifier
- 2. Overload detector
- 3. Reference amplifier
- 4. Carrier signal reference limiter
- 5. Video demodulator
- 6. Video amplifier
- 7. Video buffer amplifier
- 8. AGC detector
- IF and tuner AGC (with adjustable TOP)
- 10. Sync pulse separator
- 11. Video identification
- 12. 90° phase shift and AFC demodulator
- 13. AFC gating, AFC amplifier and AFC switch
- 14. Voltage stabilizer

1. 3-stage gain controlled IF amplifier (pins 1 and 20)

The vision IF amplifier consists of three AC-coupled differential amplifier stages. Gain control is achieved by current divider stages. The emitter feedback resistors are optimized for low noise and signal handling capability.

2. Overload detector

The overload detector is fed from the output of the third IF amplifier. As soon as the IF voltage exceeds the overload threshold in the detector, its output current reduces the IF amplification by discharging the AGC capacitor.

3. Reference amplifier

For passive video carrier regeneration an integrated differential amplifier with resistive load allows capacitive coupling of the resonant circuit for notch and tracking functions.

4. Carrier signal reference limiter

A limiter stage after the reference amplifier eliminates amplitude modulation. Its output is fed to the video demodulator.

5. Video demodulator

The video demodulator receives both the limited reference carrier signal and the IF signal. The video signal can also be switched off.

6. Video amplifier

The video amplifier is an operational amplifier with internal feedback and wide bandwidth.

7. Video buffer amplifier

The video buffer amplifier is an operational amplifier with internal feedback, wide bandwidth and frequency compensation; gain and input impedance are adapted to operate with a ceramic sound trap. The load for the sound trap is an integrated resistive divider.

8. AGC detector

The peak sync AGC detector generates a fast current pulse to discharge the AGC capacitor (gain reduction). This minimizes the video signal distortion.

To filter out the sound carrier the video signal is fed through low pass filters. After the low pass filters the video signal with attenuated sound carrier, is fed to the AGC detector. The charging current of the AGC capacitor is optimized for minimum distortion of the video signal. With positive modulation the charging current is very low and consequently the AGC time constant is large. When the video identification circuit does not detect a video signal, the charging current is increased.

9. IF and tuner AGC

The voltage on the AGC capacitor is used to control the gain of the three IF amplifier stages and to supply the tuner AGC current (open-collector). The tuner AGC TOP potentiometer at pin 2 adjusts the IF signal level from the tuner. To stabilize the IF output voltage of the tuner, IF slip (= variation of IF gain over the total tuner range) is kept at a minimum.

10. Sync pulse separator

The sync pulse separator supplies two internally-used pulses using the bandwidth limited video signal. These are the composite sync for the AFC detector and the vertical sync for the video identification output. The bandwidth is limited to reduce the noise and increase the identification sensitivity.

11. Video identification

An analog integrator monitors the duty cycle of the vertical sync pulses to identify the video signal. The integrator output is fed to a window comparator which has an open collector output stage to provide the video ident signal. The complete circuit operates in combination with the sync separator and is optimized for high sensitivity.

12. 90° phase shift and AFC demodulator

The AFC demodulator needs a 90° phase-shifted carrier. The output of the carrier signal reference limiter is fed to an active 90° phase-shift circuit. The 90° (lead) phase-shifted carrier and the IF signal are fed to the AFC demodulator. The demodulated signal and the IF signal are fed to the AFC gating stage.

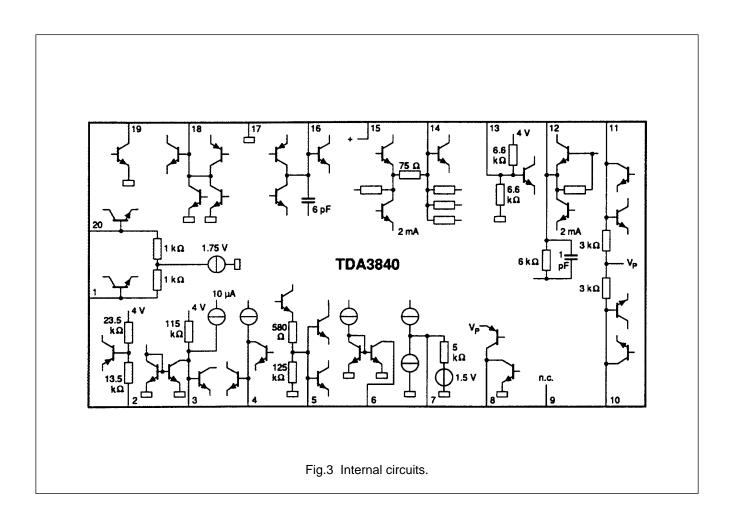
13. AFC gating, AFC amplifier and AFC switch

With negative modulated video IF signals the output of the AFC detector is gated by composite sync pulses to prevent video modulation on the AFC output. The gated signal is integrated by an AFC capacitor. The AFC amplifier converts the capacitor voltage to an AFC current (open collector sink/source output). The AFC function can be externally switched off for test purposes.

For high-performance signal handling the AFC signal can be used to track the resonant circuit as shown in Fig.11.

14. Voltage stabilizer

An integrated bandgap voltage stabilizer generates an internal supply voltage of 4 V. A decoupling capacitor reduces noise and supply voltage ripple.



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LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER		MIN.	MAX.	UNIT
V _P	supply voltage at pin 15:	SOT146	-	8.8	V
		SOT163A	-	6.0	V
V ₁₉	tuner AGC voltage		-	13.2	V
V ₈	permissible voltage at AFC out	sible voltage at AFC output		VP	V
I ₁₅	supply current	rrent		55	mA
T _{stg}	storage temperature range	ge temperature range		+ 150	°C
T _{amb}	operating ambient temperature	erating ambient temperature range		+ 70	°C
V _{ESD}	ESD sensitivity		-	± 300	V

CHARACTERISTICS

 $V_P = 5 V$ and $T_{amb} = 25 \degree C$; $f_{VC} = 38.9 \text{ MHz}$; all voltages are measured to GND (pin 17); measured in test circuit of Fig.4; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
VP	supply voltage range (pin 15)	DIL-package	4.75	5.0	8.8	V
		SO-package	4.75	5.0	6.0	V
I _P	supply current (pin 15)	V _P = 5.0 V	-	42	_	mA
RR	ripple rejection (pin 12)		30	35	_	dB
IF amplifier	-					
В	bandwidth	–3 dB	-	80	-	MHz
RI	input resistance (pins 1 and 20)		_	2	_	kΩ
CI	input capacitance (pins 1 and 20)		-	1.5	_	pF
V _{1-20(rms)}	IF input signal (RMS value)	video output –1 dB	-	70	-	μV
	maximum IF input signal	minimum G _V ; note 1	100	-	_	mV
G _V	gain control range		63	66	_	dB
IF AGC		•		•		
I ₁₈	leakage current AGC capacitor		-	-	1	μA
	charging current AGC capacitor	with video identification	-	13	-	μA
	charging current AGC capacitor	without video identification	-	35	-	μA
I _{18M}	discharging peak current capacitor		-	2	-	mA
t ₁	responsible time of IF input signal	50 dB increasing step	-	1	_	ms
	change	50 dB decreasing step	-	150	_	ms

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Tuner AGC (n	ote 2)		_ I	1	_	1
V _{1-20(rms)}	lower IF input signal for starting point of tuner take-over; see Fig.5 (RMS value)	R2 = 22 kΩ	_	-	1	mV
	upper IF input signal for starting point of tuner take-over; see Fig.5 (RMS value)	R2 = 0 Ω	50	-	-	mV
	TOP variation	60 K temperature range	-	2	3	dB
I ₁₉	tuner AGC output current	V ₁₉ = 0.5 V	1	2	-	mA
Synchronous	demodulator and video amplifier (r	ote 3)				
V ₁₄	composite video output signal		0.9	1.0	1.1	V
	sync level voltage		_	1.5	_	V
	zero carrier level voltage		_	2.6	_	V
I ₁₄	output current	DC and AC	_	-	± 1.0	mA
R ₁₄	output resistance		-	75	-	Ω
В	video bandwidth at -1 dB (pin 14)	$C_{load} \le 20 \text{ pF}$	7	8	-	MHz
V ₁₄	upper video clipping level		-	3.6	-	V
	lower video clipping level		_	0.3	-	V
Buffered vide	o output signal (see Fig.6)		·			
G	gain of video buffer		6.5	7.0	_	dB
V ₁₂	sync level clamping voltage		_	1.35	_	V
	upper video clipping level		_	4.25	_	V
	lower video clipping level		_	0.3	_	V
I ₁₂	output current	DC and AC	_	-	± 1.0	mA
R ₁₂	output resistance		-	-	10	Ω
В	video bandwidth at -1 dB (pin 12)	$C_{load} \le 20 \text{ pF}$	_	10	_	MHz
R _I	input resistance (pin 13)		-	3.3	-	kΩ
CI	input capacitance (pin 13)		_	2	-	pF

SYMBOL	PARAMETER CONDITIONS		MIN.	TYP.	MAX.	UNIT
Overall video	performance (see Fig.6)		!		-!	1
Vo	video output signal (pin 12) negative modulation; note 3		-	2	-	V
В	video bandwidth at -2 dB (pin 12)	$C_{load} \le 20 \text{ pF}$	7	8	-	MHz
S/N	signal-to-noise ratio (see Fig.7)	V ₁₋₂₀ = 10 mV; note 4	55	60	-	dB
α ₁	intermodulation for blue (note 5)	f = 1.1 MHz	56	58	-	dB
		f = 3.3 MHz	62	_	_	dB
α2	intermodulation for yellow (note 5)	f = 1.1 MHz	53	56	-	dB
		f = 3.3 MHz	60	_	_	dB
α3	signal harmonic suppression		-	26	-	dB
V ₅	video switch off voltage	note 6	_	-	1	V
α ₄	attenuation of video signal (pin 14)	video signal switched off	50	60	-	dB
ΔG	differential gain	EBU test line 330	_	2	-	%
$\Delta \Phi$	differential phase	EBU test line 330	_	2	-	deg
$\Delta V/V$	variation of video output signal (pin 14)	gain control 50 dB; $V_{1-20(rms)} = 0.3$ to 100 mV	-	-	0.5	dB
V _{res1}	residual vision carrier (pin 12)		_	1	-	mV
V _{res2}	residual second harmonic of the vision carrier (pin 12)		-	1	-	mV
Video identifio	cation	1	1	1		1
V _{1-20(rms)}	minimum IF input signal for TV identification at pin 14 (RMS value)	maximum G_V	-	20	40	μV
V ₆	video identification voltage (signal unidentified)	$V_{1-20} = <40 \ \mu V_{rms}$ $I_6 = 0.5 \ mA$	-	-	0.4	V
	video identification voltage (signal identified)	$V_{1-20} = \ge 40 \ \mu V_{rms}$ $I_6 = -1 \ \mu A$	4.5	-	-	V
T _{sync} /T _{field}	vertical pulse duty cycle		4.5	8	16	x 10 ⁻³
C/N	carrier-to-noise ratio (pin 1 and pin 20)	note 7	-	8	-	dB
I ₅	allowed leakage current		-	-	3	μA
α ₅	sync pulse suppression for correct TV signal identification		-	-	70	%
t _d	delay time of mute output signal		_	100	150	ms

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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
AFC (see Fig.9 and Fig.10); note 8						
I ₈	AFC source current output		0.16	0.19	0.22	mA
	AFC sink current output		0.16	0.19	0.22	mA
V ₈	upper output voltage		4.3	-	4.7	V
	lower output voltage		0.3	-	0.7	V
S	control steepness	QB = 40; V _{1-20(rms)} = 10 mV	-	2	-	μA/kHz
I ₇	leakage current at AFC gating		_	-	± 1	μA

Notes to the characteristics

- 1. The video signal is still gain-controlled, $V_{14(p-p)} = 1 V$, but intermodulation figures are degraded.
- 2. The starting point of tuner AGC can be adjusted by the resistor at pin 2. Fig.5 shows the AGC characteristic.
- IF input signals are RMS values measured at TOP sync (standard B/G) and with a vision carrier of 38.9 MHz (see Fig.4). The IF input signal is fed from 50 Ω via a 1:1 transformer, DSB, to pins 1 and 20. With a 10 mV_{RMS} IF input signal, the residual vision carrier is: = 10 % for white (standard B/G).
- 4. In the test circuit of Fig.4, measured and weighted according to CCIR Recommendation 567:

$$S/N = \frac{V_{14 \text{ (black to white)}}}{V_{14 \text{ noise}}(RMS, black)}$$

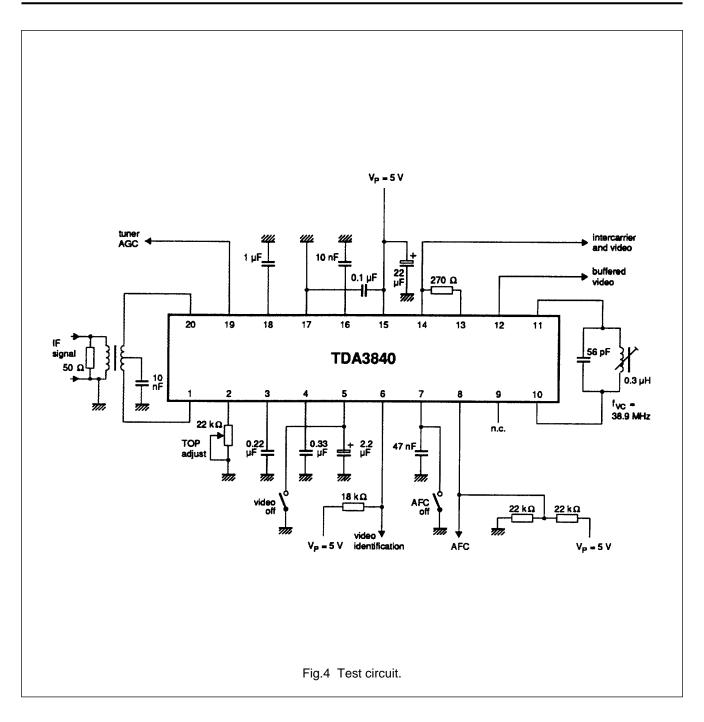
5. Intermodulation figures are defined as follows: $\alpha_1 = 20 \times \log \frac{V_o \text{at } 4.4 \text{ MHz}}{V_o \text{at } 1.1 \text{ MHz}} + 3.6 \text{ dB}$

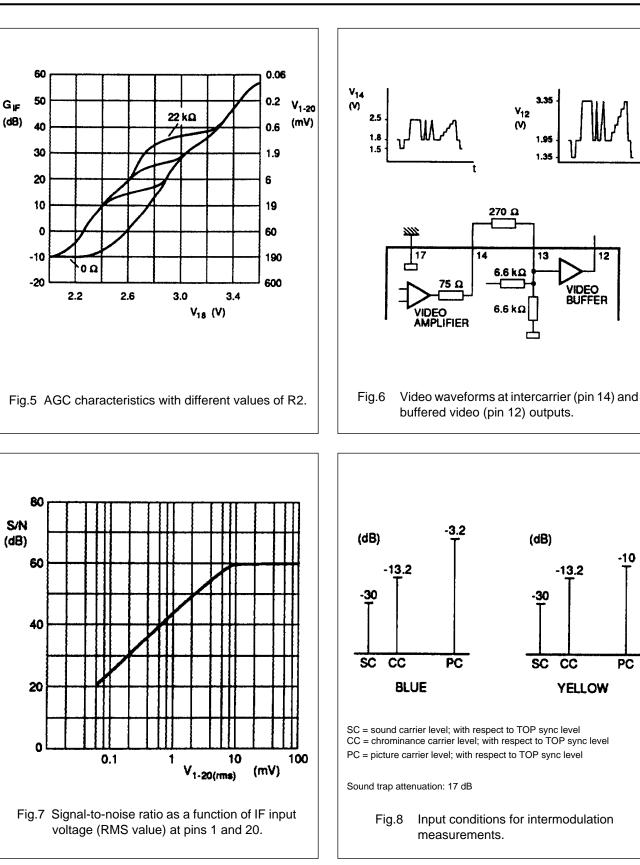
and $\alpha_2 = 20 \times log \frac{V_o at 4.4 \text{ MHz}}{V_o at 3.3 \text{ MHz}}$

- When V₅ < 1 V (short-circuited identification capacitor at pin 5) the video output signal at pin 14 is switched off. V₁₄ shifts to "zero carrier level" ("ultra white" (2.6 V) for negative modulation). During normal operation the capacitor at pin 5 should not be loaded (| I₅| ≤ 3 μA).
- 7. The C/N at the IF input (pins 1 and 20) for TV identification is defined as the RMS sync level of the vision IF signal input, relative to the RMS value of a superimposed white noise signal, with a bandwidth limited to 5 MHz.
- 8. The values for the AFC measurements depend on the Q_B of the reference circuit at pins 10 and 11. The internal phase shift is matched to a vision carrier of 38.9 MHz. The AFC function can be switched off for test purposes when pin 7 is connected to ground (V₇ = 0 V).

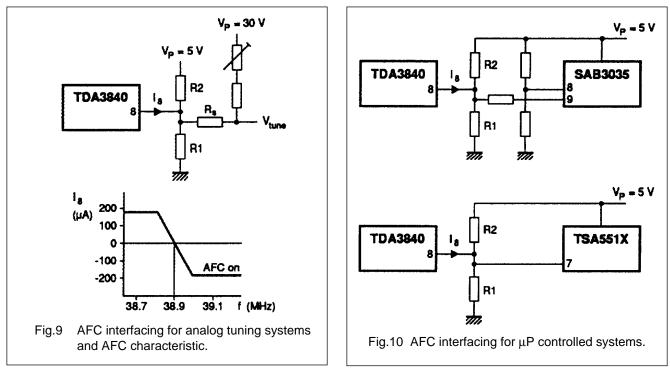
TDA3840

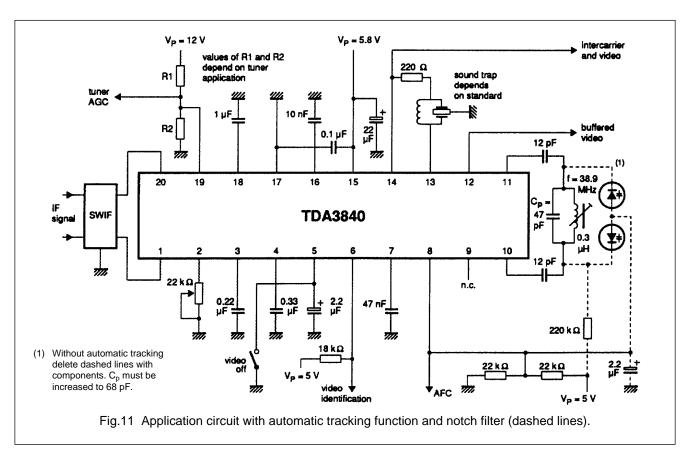
TV IF amplifier and demodulator with TV signal identification



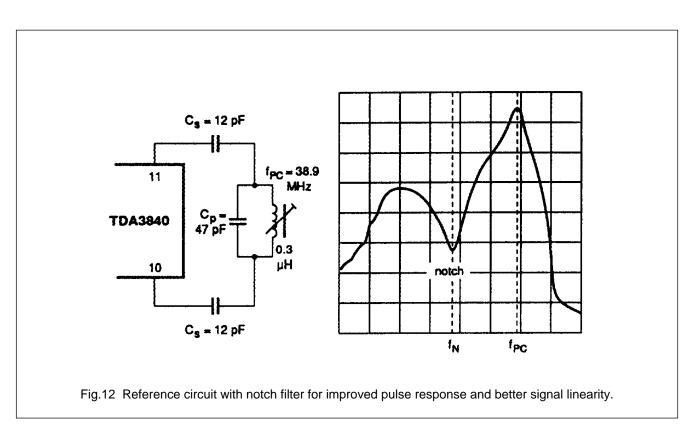








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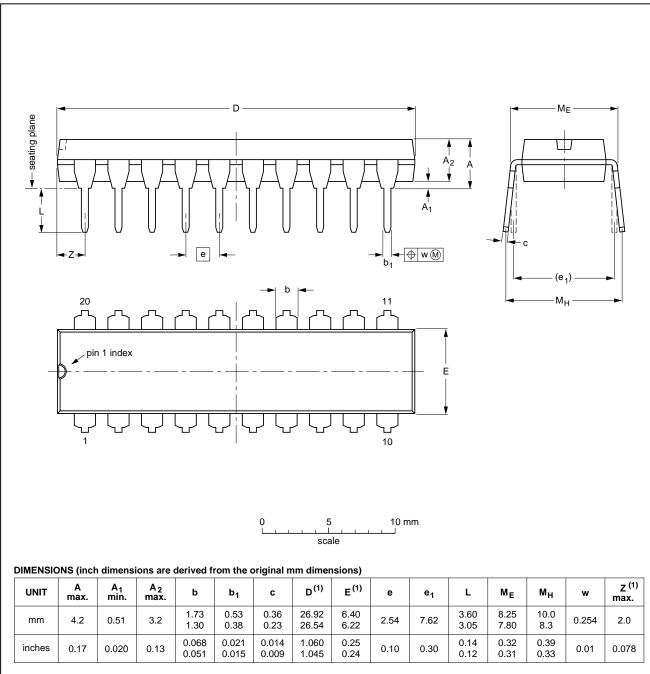
Note to figure 12

Recommended for reception of data signals e.g. in Teletext. Values in combination with SAW filter OFW G 1956 (Siemens). Curve shows combined frequency response of SAW filter and reference circuit.

For different standards C_s and C_p are calculated as follows: $C_s = 2C_p \left\{ \frac{f_{PC}^2}{f_N^2} - 1 \right\}$

PACKAGE OUTLINES

DIP20: plastic dual in-line package; 20 leads (300 mil)



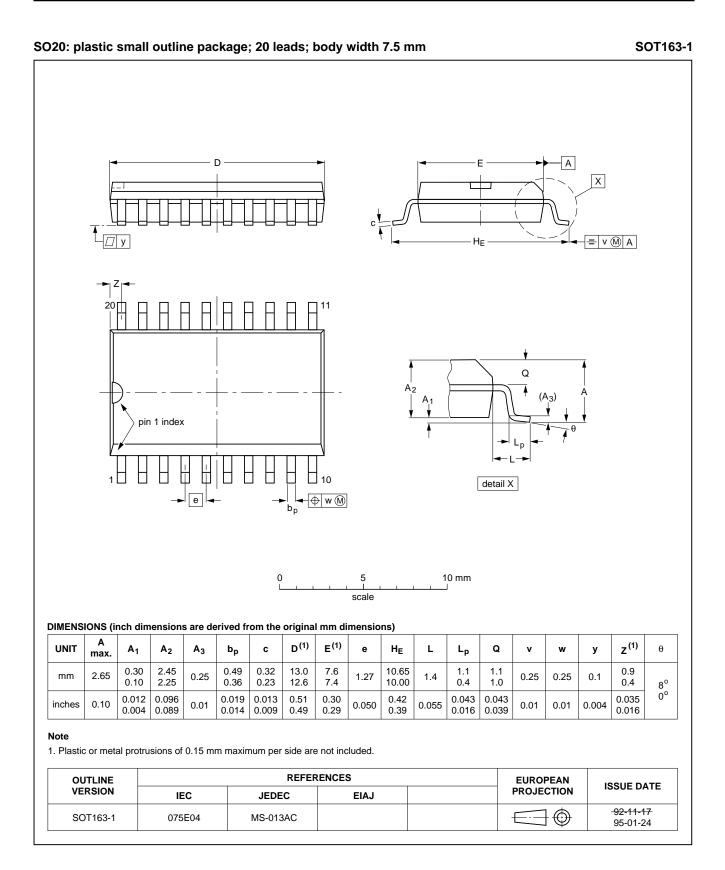
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ	PROJECTION	1550E DATE	
SOT146-1			SC603		-92-11-17- 95-05-24	

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SOT146-1



SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

DIP

SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than $300 \,^{\circ}$ C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 $^{\circ}$ C, contact may be up to 5 seconds.

SO

REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

WAVE SOLDERING

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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DEFINITIONS

Data sheet status					
Objective specification This data sheet contains target or goal specifications for product development.					
Preliminary specification	Preliminary specification This data sheet contains preliminary data; supplementary data may be published later.				
Product specification	Product specification This data sheet contains final product specifications.				
Limiting values					
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.					
Application information					

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.